

## Description

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

## Features

- $BV_{CE0} > 80V$
- $I_C = 1A$  High Continuous Collector Current
- $I_{CM} = 2.0A$  Peak Pulse Current
- Low Saturation Voltage  $V_{CE(sat)} < 500mV @ 0.5A$
- Epitaxial Planar Die Construction
- Complementary PNP types: BCX5316Q
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. "Green" Device (Note 3)**
- **The BCX5616Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

## Mechanical Data

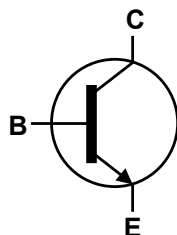
- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound  
UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Leads,  
Solderable per MIL-STD-202 Method 208 Ⓜ3
- Weight: 0.055 grams (Approximate)

## Applications

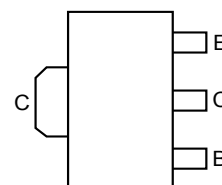
- Automotive
- Medium Power Switching or Amplification Applications
- AF Driver and Output Stages



Top View



Device Symbol



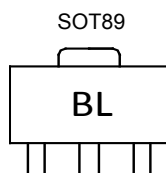
Top View  
Pin-Out

## Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BCX5616QTA	Automotive	BL	7	12	1,000
BCX5616QTC	Automotive	BL	13	12	4,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



BL = Product Type Marking Code

**Absolute Maximum Ratings** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	100	V
Collector-Emitter Voltage	$V_{CEO}$	80	V
Emitter-Base Voltage	$V_{EBO}$	6	V
Continuous Collector Current	$I_C$	1	A
Peak Pulse Collector Current	$I_{CM}$	2.0	
Continuous Base Current	$I_B$	100	mA
Peak Pulse Base Current	$I_{BM}$	200	

**Thermal Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

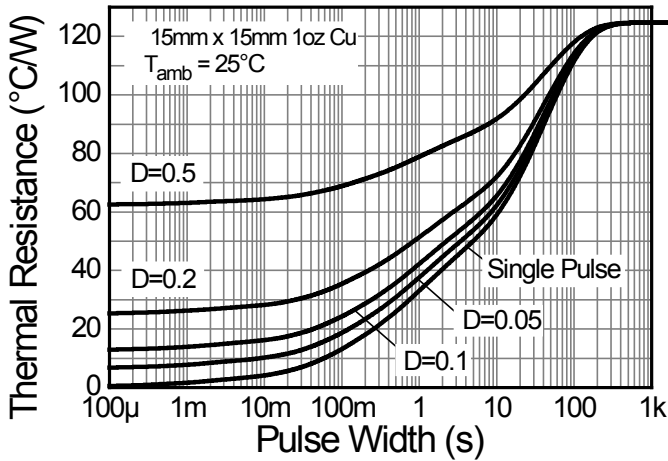
Characteristic	Symbol	Value	Unit
Power Dissipation	$P_D$	(Note 5)	1
		(Note 6)	1.5
		(Note 7)	2.0
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	(Note 5)	125
		(Note 6)	83
		(Note 7)	60
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	13	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 9)

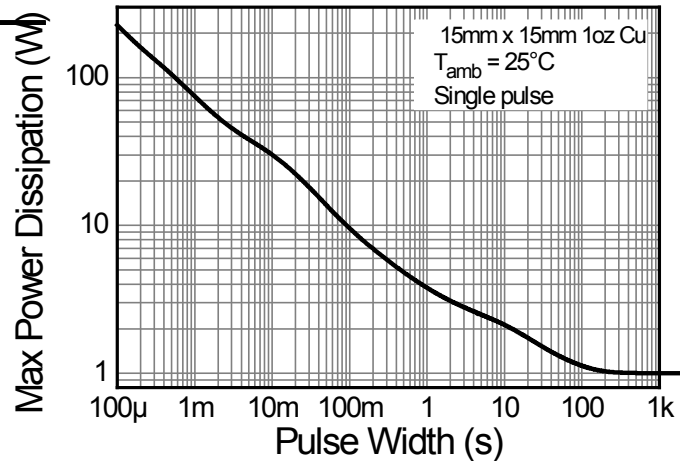
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as note (6), except the device is mounted on 25mm x 25mm 1oz copper.
  7. Same as note (6), except the device is mounted on 50mm x 50mm 1oz copper.
  8. Thermal resistance from junction to solder-point (on the exposed collector pad).
  9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

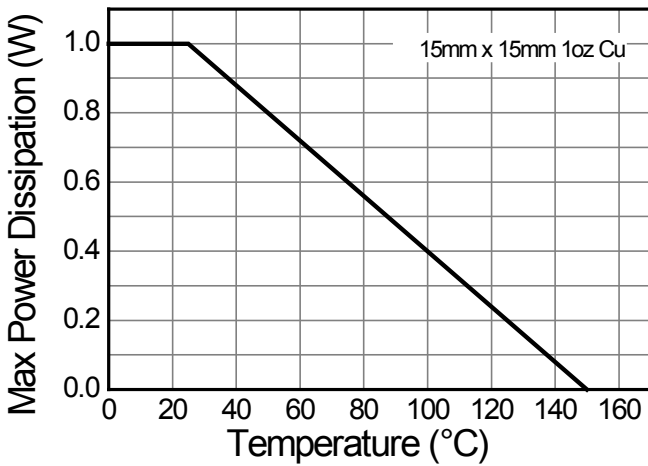
**Thermal Characteristics and Derating Information**



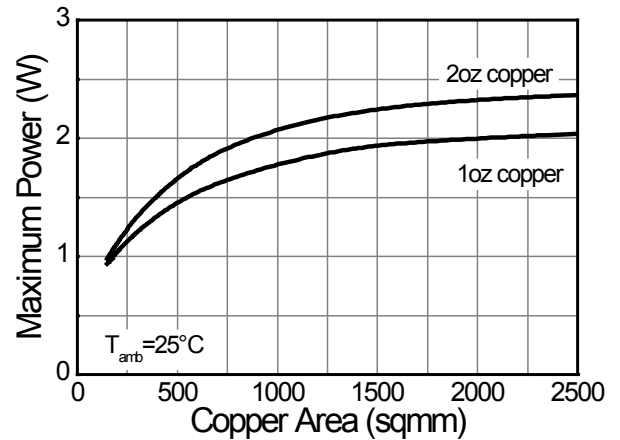
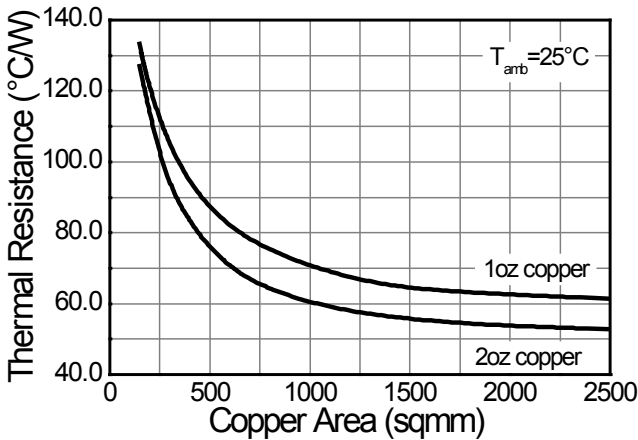
**Transient Thermal Impedance**



**Pulse Power Dissipation**



**Derating Curve**



**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	100	—	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 10)	$BV_{CEO}$	80	—	—	V	$I_C = 10\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	6	—	—	V	$I_E = 100\mu\text{A}$
Collector Cut-off Current	$I_{CBO}$	—	—	0.1 20	$\mu\text{A}$	$V_{CB} = 30\text{V}$ $V_{CB} = 30\text{V}, T_A = +150^\circ\text{C}$
Emitter Cut-off Current	$I_{EBO}$	—	—	20	nA	$V_{EB} = 5\text{V}$
Static Forward Current Transfer Ratio (Note 10)	$h_{FE}$	25 100 25	— — —	— 250 —	—	$I_C = 5\text{mA}, V_{CE} = 2\text{V}$ $I_C = 150\text{mA}, V_{CE} = 2\text{V}$ $I_C = 500\text{mA}, V_{CE} = 2\text{V}$
Collector-Emitter Saturation Voltage (Note 10)	$V_{CE(sat)}$	—	—	0.5	V	$I_C = 500\text{mA}, I_B = 50\text{mA}$
Base-Emitter Turn-On Voltage (Note 10)	$V_{BE(on)}$	—	—	1.0	V	$I_C = 500\text{mA}, V_{CE} = 2\text{V}$
Transition Frequency	$f_T$	150	—	—	MHz	$I_C = 50\text{mA}, V_{CE} = 10\text{V}$ $f = 100\text{MHz}$
Output Capacitance	$C_{obo}$	—	—	25	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$

Notes: 10. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

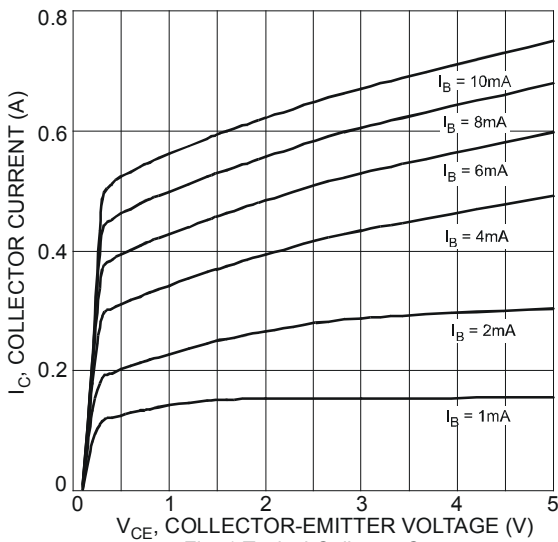


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

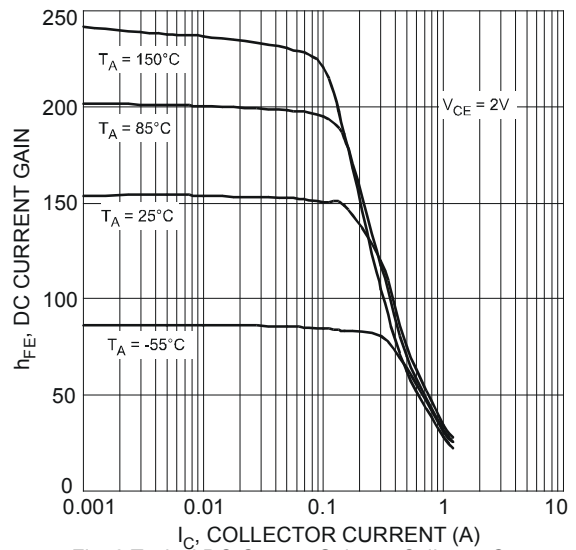


Fig. 2 Typical DC Current Gain vs. Collector Current

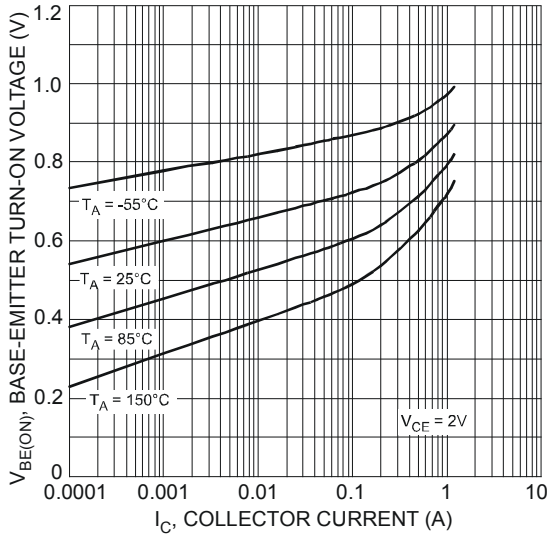


Fig. 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

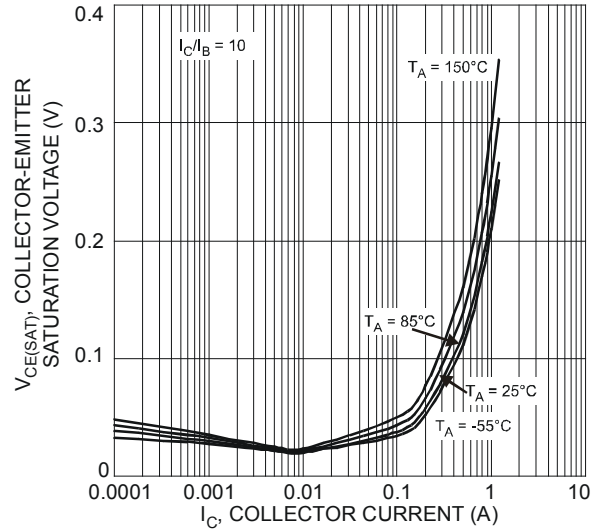


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

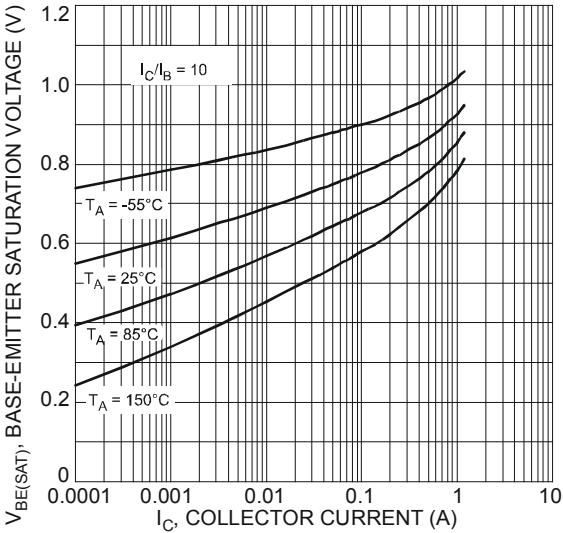


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

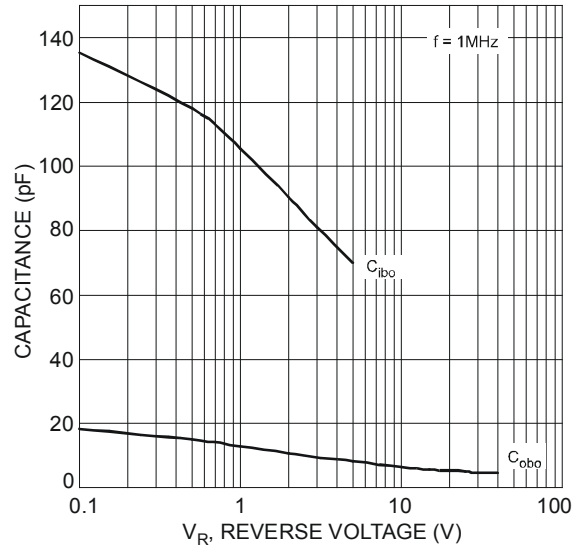


Fig. 6 Typical Capacitance Characteristics

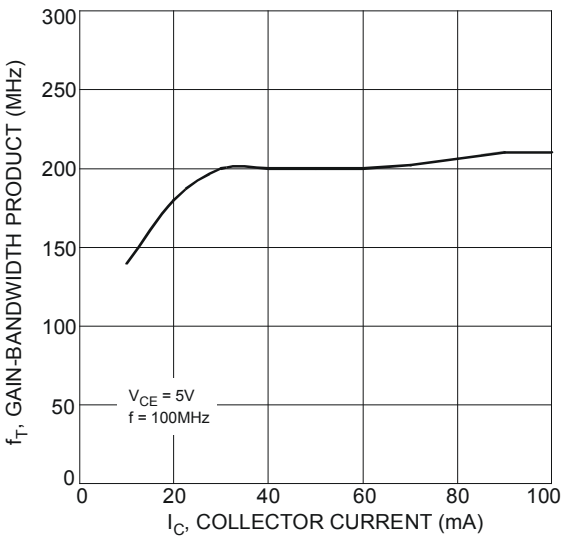
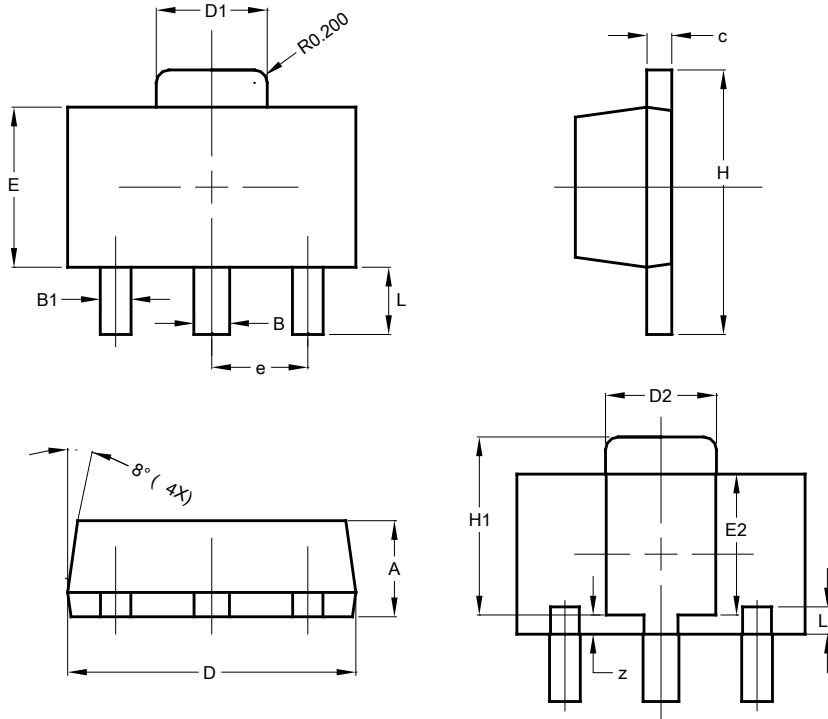


Fig. 7 Typical Gain-Bandwidth Product vs. Collector Current

## Package Outline Dimensions

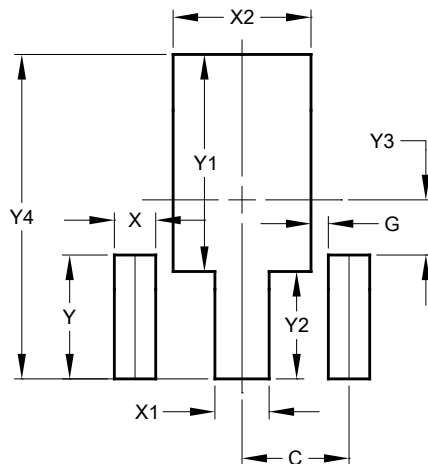
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOT89			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.50	0.62	0.56
B1	0.42	0.54	0.48
c	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.62	1.83	1.733
D2	1.61	1.81	1.71
E	2.40	2.60	2.50
E2	2.05	2.35	2.20
e	-	-	1.50
H	3.95	4.25	4.10
H1	2.63	2.93	2.78
L	0.90	1.20	1.05
L1	0.327	0.527	0.427
z	0.20	0.40	0.30
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	1.500
G	0.244
X	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

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